

RELIABILITY REPORT
FOR
MAX810LExR
PLASTIC ENCAPSULATED DEVICES

September 27, 2001

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Conclusion

The MAX810L successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX810L is a microprocessor (μP) supervisory circuit used to monitor the power supplies in μP and digital systems. It provides excellent circuit reliability and low cost by eliminating external components and adjustments when used with 5V-powered or 3V-powered circuits.

This circuit performs a single function. It asserts a reset signal whenever the V_{CC} supply voltage declines below the preset threshold, keeping it asserted for at least 140ms after V_{CC} has risen above the reset threshold. The MAX810 has an active-high RESET output. The reset comparator is designed to ignore fast transients on V_{CC} . Reset thresholds suitable for operation with a variety of supply voltages are available.

Low supply current makes the MAX810L ideal for use in portable equipment. This device comes in a 3-pin SOT-23 or SC-70 package.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Terminal Voltage (with respect to GND)	
V_{CC}	-0.3V to 6.0V
RESET	-0.3V to ($V_{\text{CC}} + 0.3\text{V}$)
Input Current, V_{CC}	20mA
Output Current, RESET	20mA
Rate of Rise, V_{CC}	100V/ μs
Operating Temperature Range	-40°C to +105°C
Storage Temp.	-65°C to +160°C
Lead Temp. (10 sec.)	+300°C
Power Dissipation	
3-Lead SOT23	320mW
3-Lead SC70	174mW
Derates above +70°C	
3-Lead SOT23	4mW/°C
3-Lead SC70	2.17mW/°C

II. Manufacturing Information

- A. Description/Function: 3-Pin Microprocessor Reset Circuit
- B. Process: S3 (SG3) - Standard 3 micron silicon gate CMOS
- C. Number of Device Transistors: SOT=275 SC70=380
- D. Fabrication Location: California or Oregon, USA
- E. Assembly Location: Malaysia or Thailand
- F. Date of Initial Production: December, 1994

III. Packaging Information

A. Package Type:	3 Lead SOT-23	3 Lead SC70
B. Lead Frame:	Alloy 42 or Copper	Alloy 42
C. Lead Finish:	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Non-Conductive epoxy
E. Bondwire:	Gold (1 mil dia.)	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-1701-0199	# 05-1601-0080
H. Flammability Rating:	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1

IV. Die Information

- A. Dimensions: 44 x 31 mils
- B. Passivation: $\text{Si}_3\text{N}_4/\text{SiO}_2$ (Silicon nitride/ Silicon dioxide)
- C. Interconnect: Aluminum/Si (Si = 1%)
- D. Backside Metallization: None
- E. Minimum Metal Width: 3 microns (as drawn)
- F. Minimum Metal Spacing: 3 microns (as drawn)
- G. Bondpad Dimensions: 5 mil. Sq.
- H. Isolation Dielectric: SiO_2
- I. Die Separation Method: Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Reliability Lab Manager)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 400 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

\triangle Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 2.71 \times 10^{-9} \quad \lambda = 2.71 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-5071) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1K**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The PW54-5 die type has been found to have all pins able to withstand a transient pulse of $\pm 2500\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 100\text{mA}$ and/or $\pm 20\text{V}$.

Table 1
Reliability Evaluation Test Results

MAX810

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		400	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	SOT23 SC70	338 77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters (generic test vehicle)		77	0

Note 1: Life Test Data may represent plastic D.I.P. qualification lots for the Shrink Small Outline package.

Note 2: Generic Process/Package Data

Attachment #3

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

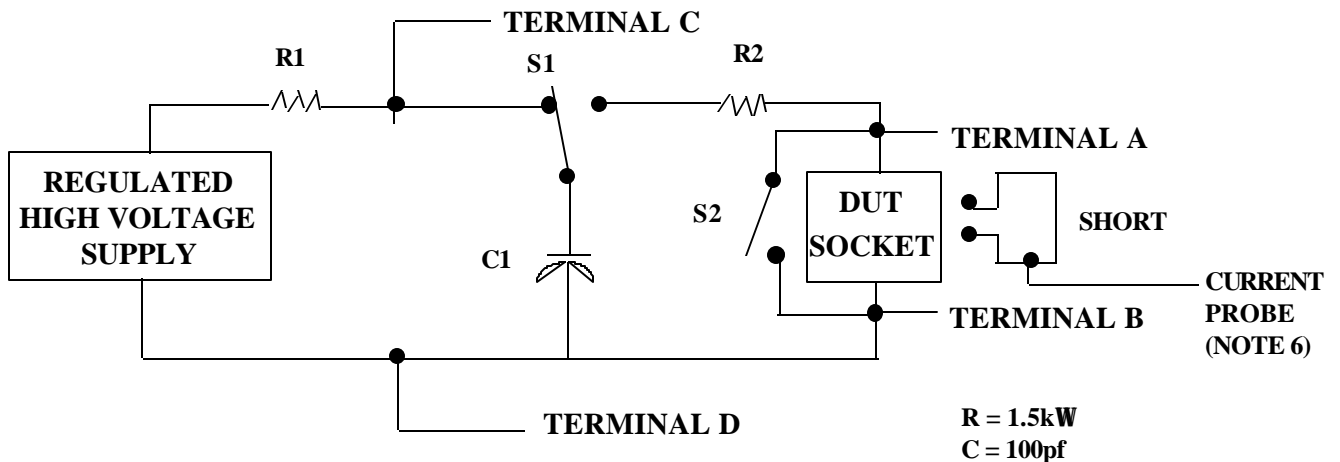
1/ Table II is restated in narrative form in 3.4 below.

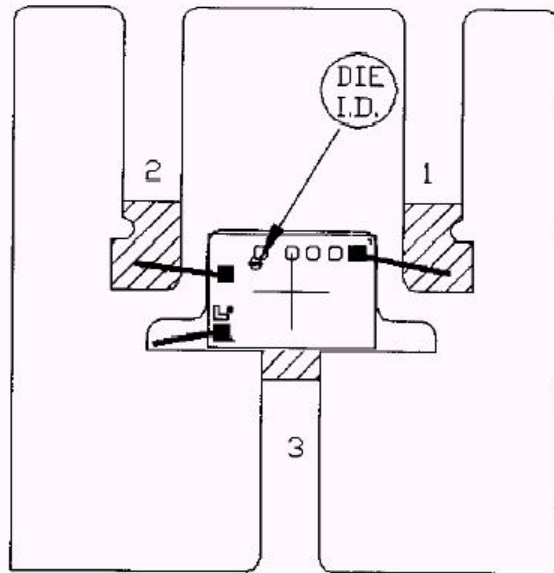
2/ No connects are not to be tested.

3/ Repeat pin combination I for each named Power supply and for ground (e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS1} , V_{BB} , GND , $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.





PKG.CODE: U3-1

APPROVALS

DATE

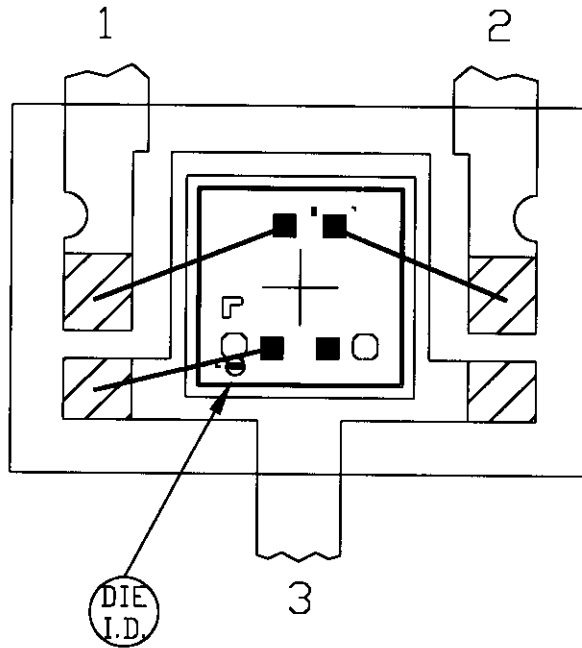
MAXIM

CAV./PAD SIZE:
45X32

PKG.
DESIGN

BUILDSHEET NUMBER:
05-1701-0199

REV:
C



SCALE: 40x

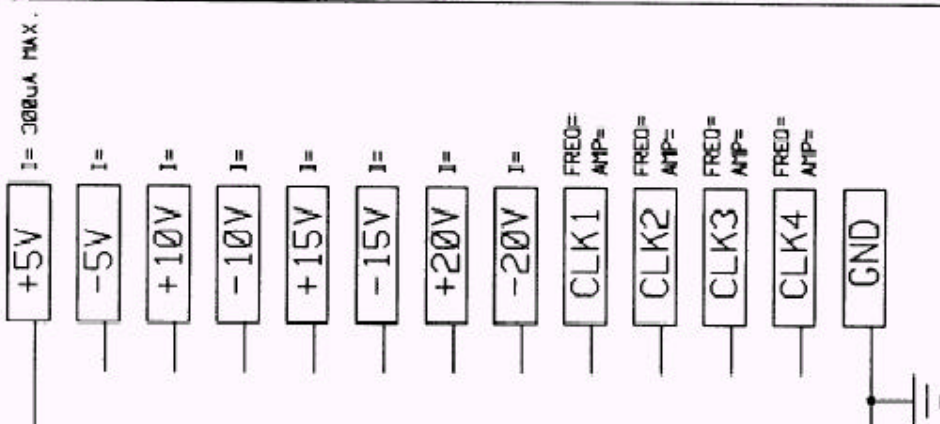
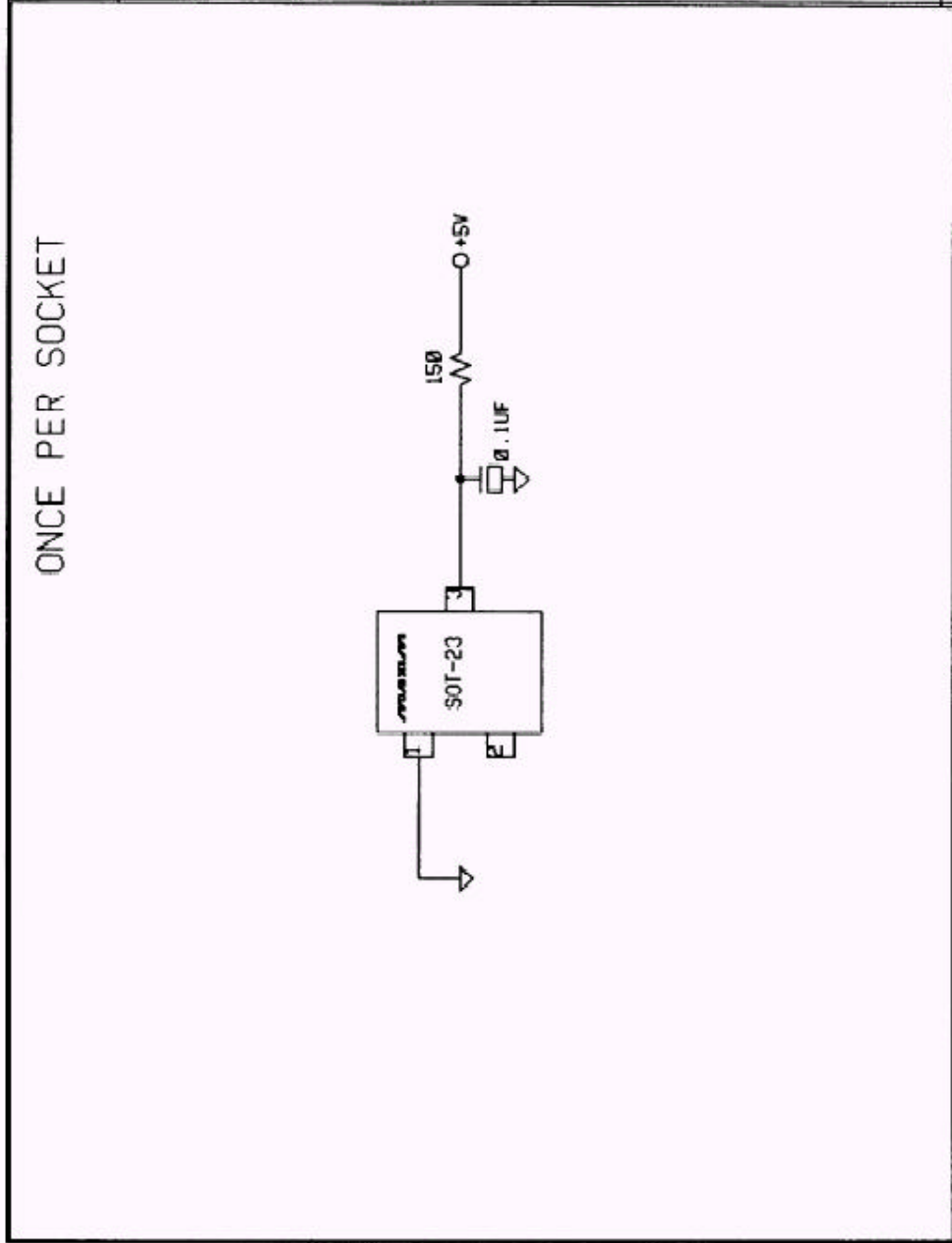
CAVITY DOWN

 BONDABLE AREA

PKG.CODE: X3-2		APPROVALS	DATE	MAXIM	
CAV./PAD SIZE: 34x35	PKG. DESIGN			BUILDSHEET NUMBER: 05-1601-0080	REV.: A

ONCE PER BOARD

ONCE PER SOCKET



-STEADY STATE LIFE TEST IS PER MIL-STD-883 METHOD 1085.
 -BURN-IN IS PER MIL-STD-883 METHOD 1015, COND. B

NOTES:

1. TEMPERATURE: 125C OR EQUIVALENT
2. TIME: 160 HOURS MIN. OR EQUIVALENT
3. ALL COMPONENTS AND MATERIAL MUST STAND 150C CONTINUOUS
4. APPROVED FOR [X] COMMERCIAL [X] HR/883

SPEC. NO. 06-5071 REV. A

DATE: 7/14/94

DRAWN BY:

MAXIM BURN-IN SCHEMATIC

DEVICE TYPE:

MAX809/810